





SCHS026E - NOVEMBER 1998 - REVISED AUGUST 2024

CD4016B Types CMOS Quad Bilateral Switch

1 Features

Texas

Instruments

- 20V digital or ± 10V peak-to-peak switching
- 280Ω typical on-state resistance for 15V operation
- Switch on-state resistance matched to within 10Ω typ over 15V signal-input range
- High on/off output-voltage ratio: 65dB typ at f _{is} = 10kHz, R_L = 10k Ω
- High degree of linearity: <0.5% distortion typ at f _{is}= 1kHz, V _{is}= $5V_{p-p}$, V _{DD} –V _{SS} \Box 10V, R _L = 10kΩ
- Extremely low off-state switch leakage resulting in very low offset current and high effective offstate resistance: 100pA typ. at V _{DD} -V _{SS} =18V, T_A=25°C
- Extremely high control input impedance (control circuit isolated from signal circuit: 10 $^{12} \Omega$ typ.
- Low crosstalk between switches: -50dB typ at f is = $0.9MHz, R_{\perp} = 1k\Omega$
- Matched control-input to signal-output capacitance: Reduces output signal transients
- Frequency response, switch on = 40MHz (typical)
- 100% tested for guiescent current at 20V
- Maximum control input current of 1µA at 18V over full package temperature range; 100nA at 18V at 25°C
- 5V, 10V, and 15V parametric ratings

2 Applications

- Analog signal switching/multiplexing signal gating
- Modulator squelch control
- Demodulator chopper
- Commutating switch
- Digital signal switching/multiplexing
- **CMOS** logic implementation
- Analog-to-digital and digital-to-analog conversion
- Digital control of frequency, impedance, phase, and analog-signal gain

3 Description

For transmission or multiplexing of analog or digital signals high-voltage types (20V rating).

CD4016B B Series types are quad bilateral switches intended for the transmission or multiplexing of analog or digital signals. Each of the four independent bilateral switches has a single control signal input which simultaneously biases both the p and n device in a given switch on or off.

The CD4016B B Series types are supplied in 14lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

Package	Information
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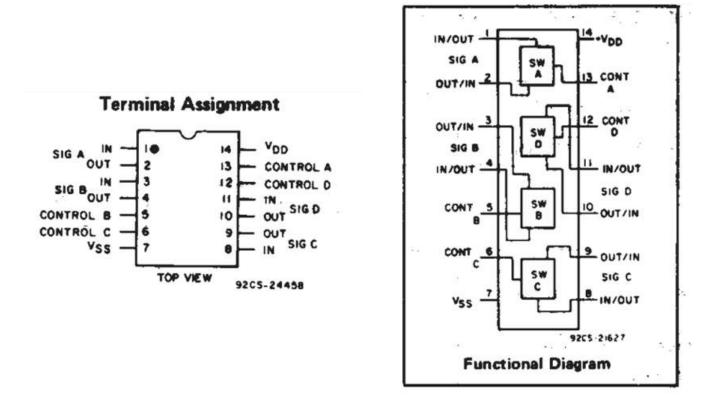
	· uonago internation									
PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾								
CD4016B	N (PDIP, 14)	19.3mm × 9.4mm								
CD4010B	D (SOIC, 14)	8.65mm × 6mm								

(1)For more information, see Section 8.

(2)The package size (length × width) is a nominal value and includes pins, where applicable.







Schematic Diagram - 1 of 4 Identical Sections



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4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾ (2)

		MIN	MAX	UNIT
V _{DD} -V _{SS}			20	V
V _{DD}	Supply voltage	-0.5	20	V
V _{SS}	_	-20	0.5	V
I _{SEL} or I _{EN}	Logic control input pin current (EN, Ax, SELx)	-30	30	mA
V _S or V _D	Source or drain voltage (Sx, D)	V _{SS} -0.5	V _{DD} +0.5	V
I _S or I _{D (CONT)}	Source or drain continuous current (Sx, D)	-20	20	mA
TJ	Junction temperature		150	°C
T _{stg}	Storage temperature	-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Rating may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Condition. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to ground, unless otherwise specified.

4.2 ESD Ratings

			VALUE	UNIT
	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/ JEDEC JS-001, all pins ⁽¹⁾	±500	N
V _(ESD)		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1500	v

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

4.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
$V_{DD} - V_{SS}^{(1)}$	Power supply voltage differential	3	18	V
V _{DD}	Positive power supply voltage	3	18	V
V_{S} or V_{D}	Signal path input/output voltage (source or drain pin) (Sx, D)	V _{SS}	V _{DD}	V
V_{SEL} or V_{EN}	Address or enable pin voltage	0	V _{DD}	V
I _S or I _{D (CONT)}	Source or drain continuous current (Sx, D)	-10	10	mA
T _A	Ambient temperature	-55	125	°C

(1) V_{DD} and V_{SS} can be any value as long as $3V \le (V_{DD} - V_{SS}) \le 24V$, and the minimum V_{DD} is met.



4.4 Thermal Information

		CD	CD4016				
THERMAL METRIC ⁽¹⁾		N (PDIP)	D (SOIC)	UNIT			
		14 PINS	14 PINS				
R _{θJA}	Junction-to-ambient thermal resistance	93.7	109.7	°C/W			
R _{0JC(top)}	Junction-to-case (top) thermal resistance	72.5	69.4	°C/W			
R _{θJB}	Junction-to-board thermal resistance	68.0	67.9	°C/W			
Ψ_{JT}	Junction-to-top characterization parameter	50.3	25.8	°C/W			
Ψ_{JB}	Junction-to-board characterization parameter	67.3	67.1	°C/W			

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

4.5 Electrical Characteristics

Over operating free-air temperature range, $V_{SUPPLY} = \pm 5V$, and $R_L = 100\Omega$, (unless otherwise noted)⁽¹⁾

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SIGNAL	. INPUTS (VIS) AND OUTPUTS (V	/ _{os})					
			T _A = -55°C			5	
			$T_A = -40^{\circ}C$			5	
		V _{is} = 0 to 5V V _{DD} = 5V	T _A = 25°C		4.5	6	
			T _A = 85°C			7.5	
			T _A = 125°C			7.5	
		T _A = -55°C			6		
		$T_A = -40^{\circ}C$			6		
		V _{is} = 0 to 10V V _{DD} = 10V	T _A = 25°C		5	7	
		T _A = 85°C			15		
_	Quiescent Device Current		T _A = 125°C			15	μA
DD			$T_A = -55^{\circ}C$			7	μ
			$T_A = -40^{\circ}C$			7.2	
		V _{is} = 0 to 15V V _{DD} = 15V	T _A = 25°C		6	8	
			T _A = 85°C			30	
			T _A = 125°C			30	30
			$T_A = -55^{\circ}C$			8.5	
		$T_A = -40^{\circ}C$			8.5		
		V _{is} = 0 to 20V V _{DD} = 20V	T _A = 25°C		6.5	9	
			T _A = 85°C			150	
			T _A = 125°C			150	



4.5 Electrical Characteristics (continued)

Over operating free-air temperature range, $V_{SUPPLY} = \pm 5V$, and $R_L = 100\Omega$, (unless otherwise noted)⁽¹⁾

	PARAMETER		TEST CC	ONDITIONS		MIN TYP	MAX	UNIT	
		$T_A = -55^{\circ}C$					600		
			V _{DD} = 10V	$T_A = -40^{\circ}C$			610		
			$V_{is} = V_{SS}$ or	T _A = 25°C		250	660		
			V _{DD}	T _A = 85°C			840		
				T _A = 125°C			960		
				T _A = -55°C			1870		
			V _{DD} = 10V	$T_A = -40^{\circ}C$			1900		
			V _{is} = 4.75 to	T _A = 25°C			2000		
		to	5.75V	T _A = 85°C			2380	1	
r	ON Registeres r. Max	to (V _{DD} +V _{SS})/2 ,		T _A = 125°C			2600		
r _{ON}	ON Resistance r _{ON} Max	$V_{\rm C} = V_{\rm DD}$,		T _A = -55°C			360	Ω	
		RL = 10kΩ	V _{DD} = 15V	$T_A = -40^{\circ}C$			370		
			$V_{is} = V_{SS}$ or	T _A = 25°C		200	400		
			V _{DD}	T _A = 85°C			520		
				T _A = 125°C			600		
				T _A = -55°C			775		
			V _{DD} = 15V V _{is} = 7.25 to 7.75V	T _A = -40°C			790	4	
				T _A = 25°C			850		
				T _A = 85°C			1080		
				T _A = 125°C			1230		
		to $(V_{DD}+V_{SS})/2$, $V_C = V_{DD}$, RL = 10k Ω		V _{DD} = 5V V _{SS} = 0V	T _A = 25°C		580	7000	
r	ON Resistance r _{ON} Max		V _{DD} = 7.5V V _{SS} = -7.5V	T _A = 25°C		200	280	Ω	
r _{ON}	ON Resistance ION Max		V _{DD} = 5V V _{SS} = -5V	T _A = 25°C		250	580		
			V _{DD} = 2.5V V _{SS} = -2.5V	T _A = 25°C		520	30000		
			V _{DD} = 5V			15			
∆R _{ON}	On-state resistance difference between any two switches	$R_L = 10kΩ$, $V_C = V_{DD}$	V _{DD} = 10V			10		Ω	
			V _{DD} = 15V			5			
THD	Total Harmonic Distortion		$V_{\rm SS} = -5V, V_{\rm is}$ 0kΩ, f _{is} = 1kHz	_{s(p-p)} = 5V (sine w sine wave	vave centered	0.4		%	
BW	-3-dB cutoff frequency (switch on)	V _C = V _{DD} = 5V on 0V), R _L = 1	$V, V_{SS} = -5V, V_{is}$ k Ω	_{s(p-p)} = 5V (sine w	vave centered	40		MHz	
OISO	-50-dB feedthrough frequency (switch off)	$V_{\rm C} = V_{\rm DD} = 5V_{\rm OD}$ on 0V), R _L = 1		_{s(p-p)} = 5V (sine w	vave centered	1.25		MHz	
				T _A = -55°C		-0.1	0.1		
		V _{DD} = 18V		T _A = -40°C		-0.1	0.1	1	
I _{is}	Input/Output Leakage Current (switch off)	V _C = 0V V _{is} = 18V, V _{os}	= 0V	T _A = 25°C		0.000 1	0.1	μA	
		$V_{is} = 0V, V_{os} =$	18V	T _A = 85°C		-1	1	-	
				T _A = 125°C		-1	1		
XTALK	–50-dB crosstalk frequency	$V_{\rm C} = V_{\rm DD} = 5V_{\rm OD}$ on 0V), R _I = 1		_{s(p-p)} = 5V (sine w	vave centered	0.9		MHz	



4.5 Electrical Characteristics (continued)

Over operating free-air temperature range, $V_{SUPPLY} = \pm 5V$, and $R_L = 100\Omega$, (unless otherwise noted)⁽¹⁾

PARAMETER			TEST CONDITIONS			TYP	MAX	UNIT
		V _C = V _{DD} , V _{SS}	V _{DD} = 5V			40	100	
		= GND V _{IS} = Square	V _{DD} = 10V			20	40	
t _{pd}	Propagation delay $V_{IS} = Square$ Wave 0 to V_{DD} , $C_L =$ $50pF$, $R_L =$ $200k\Omega$		V _{DD} = 15V			15	30	ns
C _{IS}	Input capacitance	V _{DD} = 5V, VC =	= V _{SS} = -5V			4		pF
Cos	Output capacitance	V _{DD} = 5V, VC =	= V _{SS} = -5V			4		pF
C _{IOS}	Feed through	V _{DD} = 5V, VC =	= V _{SS} = -5V			0.2		pF
				T _A = -55°C			0.9	
		I _{is} < 10µA, V _{is} = V _{SS} , V _{OS}	$V_{DD} = 5V$	T _A = -40°C			0.9	
V _{ILC}	Control input, low voltage (ma	$= V_{DD}$, and V_{is}	V _{DD} = 10V	T _A = 25°C			0.7	V
		= V _{DD} , V _{OS} = V _{SS}	V _{DD} = 15V	T _A = 85°C			0.4	
		VSS		T _A = 125°C			0.4	
			V _{DD} = 5V	- I	3.5			V
V _{IHC}	Control input, high voltage	See Figure 10	V _{DD} = 10V		7			V
			V _{DD} = 15V		11			V
I _{IH}	Input High Lekaage		V _{DD} = 18V			0.5	1	μA
IIL	Input Low Leakage		V _{DD} = 18V		-1	-0.1		μA
	Crosstalk (control input to sig output)	$\begin{array}{c} V_{C} = 10V\\ (square\\ wave), t_{r}, t_{f} =\\ 20ns, R_{L} =\\ 10k\Omega \ V_{DD} =\\ 10V \end{array}$	V _{DD} = 10V			50		mV
		t _r , t _f = 20ns	V _{DD} = 5V			35	70	ns
	Turn-on propagation delay	$C_{L} = 50 pF,$	V _{DD} = 10V			20	40	ns
		$R_L = 1k\Omega$	V _{DD} = 15V			15	30	ns
	Maximum control input repeti rate	$\begin{array}{c} V_{IN}=V_{DD},C_{L}\\ =50pF,R_{L}=\\ 1k\Omega\\ V_{C}=10V\\ (square wave\\ centered on\\ 5V,t_{r},t_{f}=\\ 20ns,V_{os}=\\ 1/2V_{os}at\\ 1kHz \end{array}$	V _{DD} = 10V		10		MHz	
C _{IN}	Input Capacitance		1			5	7.5	pF



4.5 Electrical Characteristics (continued)

Over operating free-air temperature range, $V_{SUPPLY} = \pm 5V$, and $R_L = 100\Omega$, (unless otherwise noted)⁽¹⁾

	PARAMETER		TEST CONDITIONS	MIN TYP MAX	UNIT
			$T_A = -55^{\circ}C$	0.25	
			T _A = -40°C	0.2	
		V _{DD} = 5V V _{is} = 0V	T _A = 25°C	0.2	mA
		VIS OV	T _A = 85°C	0.12	
			T _A = 125°C	0.14	
			T _A = -55°C	-0.25	
			$T_A = -40^{\circ}C$	-0.2	
		V _{DD} = 5V V _{is} = 5V	T _A = 25°C	-0.2	mA
		VIS OV	T _A = 85°C	-0.12	
			T _A = 125°C	-0.14	
			T _A = -55°C	0.62	
			$T_A = -40^{\circ}C$	0.5	
		V _{DD} = 10V V _{is} = 0V	T _A = 25°C	0.5	mA
		V _{IS} = 0 V	T _A = 85°C	0.3	
			T _A = 125°C	0.35	
S	Switch input current		$T_A = -55^{\circ}C$	-0.62	
			$T_A = -40^{\circ}C$	-0.5	
		V _{DD} = 10V V _{is} = 10V	T _A = 25°C	-0.5	m/
		V _{IS} = 10V	T _A = 85°C	-0.3	
			T _A = 125°C	-0.35	
			$T_A = -55^{\circ}C$	1.8	
			$T_A = -40^{\circ}C$	1.4	
		V _{DD} = 15V V _{is} = 0V	$T_A = 25^{\circ}C$	1.5	m
		v _{is} – ov	T _A = 85°C	1	
			T _A = 125°C	1.1	
			T _A = -55°C	-1.8	
			$T_A = -40^{\circ}C$	-1.4	
		V _{DD} = 15V V _{is} = 15V	$T_A = 25^{\circ}C$	-1.5	m/
		v _{is} = 15v	T _A = 85°C	-1	
			T _A = 125°C	-1.1	
		V _{DD} = 5V V _{is} = 0V		0.4	V
		V _{DD} = 5V V _{is} = 5V		4.6	V
	$V_{DD} = 10V$ $V_{is} = 0V$		0.5	V	
os	Switch output voltage	V _{DD} = 10V V _{is} = 10V		9.5	V
	V _{DD} = 15V V _{is} = 0V		1.5	V	
		V _{DD} = 15V V _{is} = 15V		13.5	V

(1) Peak-to-Peak voltage symmetrical about $(V_{DD} - V_{EE})$ / 2.



4.6 Electrical Characteristics

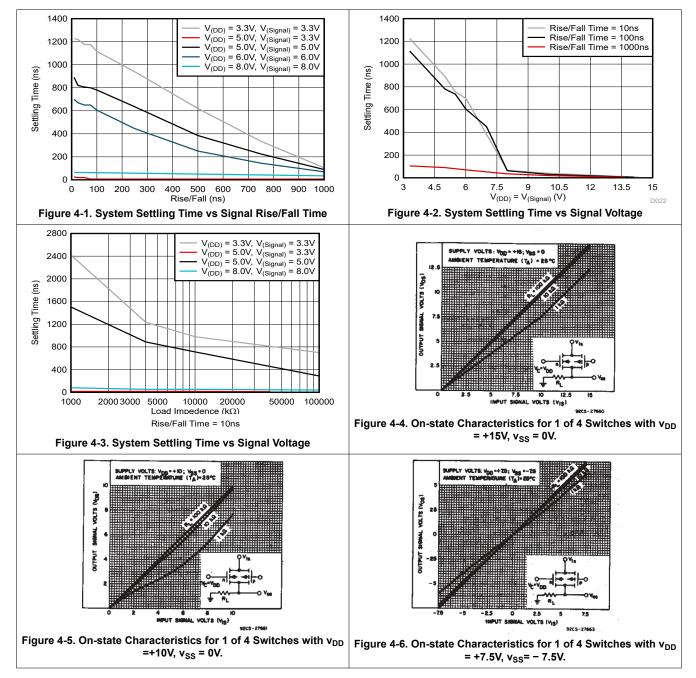
	TEST CONDITIONS				LIMIT	LIMITS AT INDICATED TEMPERATURES (°C)					
CHARACTERISTIC			V _{IN} (V)	V _{DD} (V)	+25						
					-55	-40	+85	+125	TYP	MAX	
			0,5	5	025	0.25	7.5	7.5	0.01	0.25	-
Quiescent Device			0,10	10	0.5	0.5	15	15	0.01	0.5	μA
Current, I _{DD}			0,15	15	1	1	30	30	0.01	1	-
			0,20	20	5	5	150	150	0.02	5	
Signal Inputs (V _{is}) and Ou				40	000	0.40	0.40		1	000	
	V _C =V _{DD}	V _{is} =V _{DD} or V _{SS}		10	600	610	840	960	-	660	-
	$R_L = 10k\Omega$ Returned to	V _{is} =4.75 to 5.75V		10	1870	1900	2380	2600	-	2000	Ω
Resistance, r _{on} MAX	$\frac{V_{DD} - V_{SS}}{2}$	V _{is} =V _{DD} or V _{SS}		15	360	370	520	600	-	400	-
	2	V _{is} =7.25 to 7.75V		15	775	790	1080	1230	-	850	
∆On-State				5	-	-	-	-	15	-	
	$R_L = 10k\Omega, V_C = V_{DD}$			10	-	-	-	-	10	-	Ω
Any 2 Switches, Δr _{on}				15	-	-	-	-	5	-	
Total Harmonic N Distortion, THD f	$V_{C}=V_{DD}$ =5V, V_{SS} = –5V, $V_{is(p\text{-}p)}$ = 5V (Sine wave centered on 0V) R_{L} = 10kG f_{is} = 1kHz sine wave			n 0V) R _L = 10kΩ	, _	-	-	-	0.4	-	%
-3dB Cutoff Frequency (Switch on)	V _C =V _{DD} =5V, V _{SS} =-5V,	V _{is(p-p)} (Sine wave c	centered on 0V)	R _L =1kΩ,	-	-	-	-	40	-	MHz
-50dB Feed-through Frequency (Switch off)	V _C =V _{SS} = -5V, V _{is(p-p)} =5	V (Sine wave cente	ered on 0V) R _L =	1 lkΩ	-	-	-	-	1.25	-	MHz
Input/Output	$V_{\rm C} = 0V$										
Leakage Current	V _{is} = 18V, V _{OS} = 0V;			18	±0.1	1 ±0.1	±1	±1	10 ⁻⁴	±0.1	μA
(Switch off) I _{is} MAX	V _{is} = 0V, V _{OS} = 18V										
	$V_{\rm C}({\rm A}) = V_{\rm DD} = +5V, V_{\rm C}({\rm B})$	3) = V _{SS} =-5V, V _{is} (A)= 5V _{p-p} , 50Ω				-		0.9	-	
-50dB Crosstalk Frequency	source				-			-			MHz
	R _L = 1kΩ										
F	R _I = 200kΩ			5	-	-	-	-	40	100	
Propagation	$V_{\rm C} = V_{\rm DD}, V_{\rm SS} = {\rm GND}, 0$	C _L = 50pF		10	-	-	-	-	20	40	1
Delay (Signal Input to	V _{is} = Square Wave 0 to	V _{DD}									ns
Signal Output) t _{pd} t	t _r , t _f = 20ns			15	-	-	-	-	15	30	
Capacitance:					_	_	-	-	4	_	
	V _{DD} = +5V				-	-	-	-	4	-	pF
Feed-through, C _{ios}	V _C =V _{SS} =-5V				_	_	_	_	0.2	_	1
Control (V _C)											
	ll _{is} < 10 μA										
· · · · · · · · · · · · · · · · · · ·	V _{is} = V _{SS} , V _{OS} = V _{DD} ar	nd $V_{is} = V_{DD}, V_{OS} =$	V _{SS}	5,10, 15	0.9	0.9	0.4	0.4	-	0.7	V
Control Innut Lligh				5		1	-	-	3	3.5 (Min.)	
Control Input High Voltage, V _{IHC}	See Figure 4-8			10						7 (Min.)	_
				15		_				11 (Min.)	
Input Current I	Input Current, I _{IN} (MAX)	V _{is} □ V _{DD}		_							
(MAX)	$V_{DD} - V_{SS} = 18V$			18	±0.1	±0.1	±1	±1	±10 ⁻⁵	±0.1	μA
	$V_{CC} \Box V_{DD} - V_{SS}$										
Crosstelly (Control	V _C = 10V (Sq. Wave)			_							
Input to Signal Output)	t _r , t _f = 20ns			10	-	-	-	-	50	-	mV
	R _L = 10kΩ						1	1			
Turn On Propagation	Turn-On Propagation D	elay t _r , t _f = 20ns		5	-	-		-	35	70	4
Delay	C _L = 50pF			10	-	-	-	-	20	40	ns
F	R _L = 1kΩ			15	-	-	-	-	15	30	



4.6 Electrical Characteristics (continued)

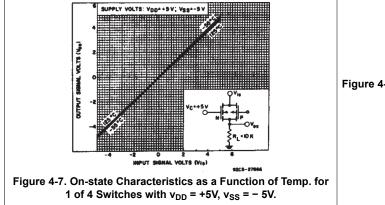
	TEST CONDITION	ONS		LIMITS AT INDICATED TEMPERATURES (°C)						
CHARACTERISTIC		V AA	V _{DD} (V)				+25		UNITS	
		V _{IN} (V)	VDD (V)	-55	-40	+85	+125	TYP	MAX	
Maximum Control Input Repetition Rate	$ \begin{array}{l} \mbox{Maximum Control Input Repetition Rate} \\ V_{is} = V_{DD} < V_{SS} = GND, R_L = 1 \mbox{k}\Omega \mbox{ to GND, } C_L \\ 10 V(\mbox{Square wave centered on 5V}) \\ t_r, t_f = 20 \mbox{ns}, V_{OS} = \frac{1}{2} \mbox{ V}_{OS} \mbox{ at 1kHz} \end{array} $	_ = 50pF, V _C =	10	-	_	_	_	10	_	MHz
Input Capacitance, C _{IN}				-	-	-	-	5	7.5	μF

4.7 Typical Characteristics

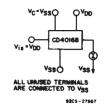


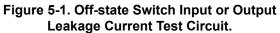


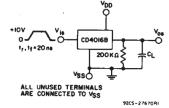
4.7 Typical Characteristics (continued)



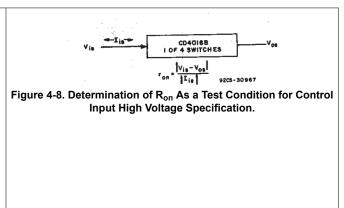
5 Parameter Measurement Information











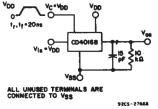


Figure 5-2. Test Circuit for Square-wave Response.

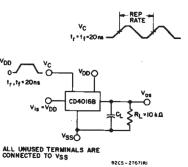
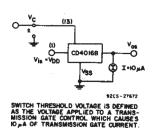


Figure 5-4. MAX Control-input Repetition Rate.







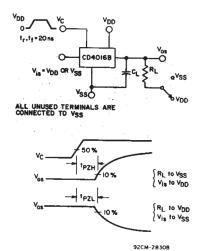


Figure 5-6. Turn-On Propagation Delay-control Input.



6 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

6.1 Documentation Support

6.1.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

6.1.2 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

6.1.3 Trademarks

TI E2E[™] is a trademark of Texas Instruments.

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6.1.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

6.1.5 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

С	hanges from Revision D (May 2024) to Revision E (August 2024)	Page
•	Added Settling Time plots	10

С	hanges from Revision C (September 2003) to Revision D (May 2024)	Page
•	Increased IDD max/typ for the lower Temperature cases	5
•	Changed typical IIH to 0.5µA	5
	Changed typical IIL to -0.1µA	

8 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	(1)		•			(_/	(6)	(-)		()	
5962-9064001CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9064001CA CD4016BF3A	Samples
CD4016BE	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4016BE	Samples
CD4016BEE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4016BE	Samples
CD4016BF	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4016BF	Samples
CD4016BF3A	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9064001CA CD4016BF3A	Samples
CD4016BM	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	CD4016BM	
CD4016BM96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4016BM	Samples
CD4016BMT	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	CD4016BM	
CD4016BNSR	NRND	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4016B	
CD4016BPW	NRND	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM016B	
CD4016BPWR	NRND	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM016B	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4016B, CD4016B-MIL :

- Catalog : CD4016B
- Military : CD4016B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

*All dimensions are nominal

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4016BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4016BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4016BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4016BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

25-Sep-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4016BM96	SOIC	D	14	2500	353.0	353.0	32.0
CD4016BM96	SOIC	D	14	2500	356.0	356.0	35.0
CD4016BNSR	SO	NS	14	2000	356.0	356.0	35.0
CD4016BPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

TEXAS INSTRUMENTS

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25-Sep-2024

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD4016BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4016BEE4	N	PDIP	14	25	506	13.97	11230	4.32
CD4016BPW	PW	TSSOP	14	90	530	10.2	3600	3.5

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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